LTCC

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Low Temperature Cofired Ceramic

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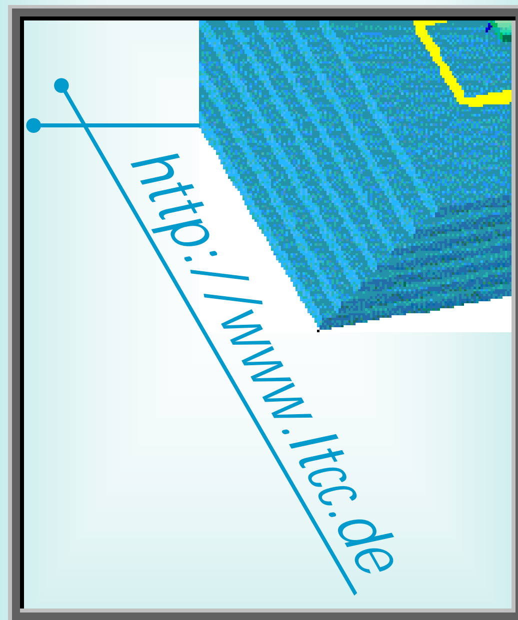
An Introduction and Overview



Version: 20. December 2001

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LTCC – An Introduction and Overview

by Reinhard Kulke and the LTCC team of IMST

This brochure has been prepared by the LTCC staff of the IMST GmbH, Germany. The research has been funded by the European Community in the Brite-Euram III project "RAMP" (Rapid Manufacture of Microwave and Power Modules, BE-97-4883), which runs from October 1998 to September 2001.

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Price for paper-back: 150 €

Price for PDF-file: 250 €

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